

Title (en)

ASSEMBLY FOR AND METHOD OF PACKAGING INTEGRATED DISPLAY DEVICES

Title (de)

VERFAHREN UND VORRICHTUNG ZUM BEHAUSEN INTEGRIERTER ANZEIGEN

Title (fr)

ENSEMBLE ET PROCEDE DE CONDITIONNEMENT DE DISPOSITIFS DE VISUALISATION INTEGREEE

Publication

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Application

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Abstract (en)

[origin: WO9935681A1] A packaging assembly for compactly sealing a display chip device is disclosed. The packaging assembly includes at least a first cover member and a seal assembly for sealing the display chip device within an enclosure. A method of packaging a display chip device is also disclosed.

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IPC 8 full level

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